

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chun-Ming Wu	09/18/2013
RECEIVING PARTY DATA	
Name:	Asia Vital Components Co., Ltd.
Street Address:	7F.-3, No. 24, Wucyuan 2nd Road
Internal Address:	Sinjhuang District
City:	New Taipei City
State/Country:	TAIWAN
Postal Code:	R.O.C.
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14037947
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ATTORNEY DOCKET NUMBER:	20110104.DIV/TH/ACL
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Signature:	/C. G. Mersereau/
Date:	09/26/2013
Total Attachments: 1 source=ASGN#page1.tif	

CH \$40.00 14037947

ASSIGNMENT

WHEREAS, I Chun-Ming Wu of 7F.-3, No. 24, Wucyuan 2nd Road, Sinhuang District, New Taipei City, Taiwan, R.O.C., hereafter referred to as applicant, have invented certain new and useful improvements in Thermal Module and Manufacturing Method Thereof for which an application for a United States Patent was executed on September 25, 2013; and

WHEREAS, Asia Vital Components Co., Ltd. herein referred to as "Assignee" whose mailing address is 7F.-3, No. 24, Wucyuan 2nd Road, Sinhuang District, New Taipei City, Taiwan, R.O.C. is desirous of acquiring the entire right, title and interest in and to said invention, and in and to and under any and all Letters Patent to be obtained thereon;

NOW, THEREFORE, for and in consideration of one Dollar (\$1.00) and other good and valuable considerations, the receipt of which is hereby acknowledged, I the applicant have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the Assignee, its successors and assigns the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all of my rights under the International Convention, and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the Assignee in accordance herewith.

Upon said consideration, I do hereby covenant and agree with the said Assignee, its successors and assigns, that I will not execute any writing or do any act whatsoever conflicting with these presents, and that I or my executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

(1) Date September 18, 2013

Signature of Inventor
Name of Inventor:

Chun-Ming Wu
Chun-Ming Wu